TOSHIBA Field Effect Transistor Silicon P-Channel MOS Type (Ultra-High-speed U-MOSIII)

TPCA8107-H

High Efficiency DC / DC Converter Applications
Notebook PC Applications
Portable Equipment Applications
CCFL Inverter Applications

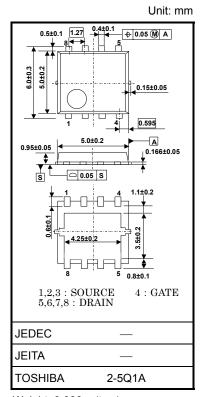
- Small footprint due to a small and thin package
- High speed switching
- Small gate charge: QSW = 9.7 nC (typ.)
- Low drain-source ON-resistance: RDS (ON) = $24m\Omega$ (typ.)
- High forward transfer admittance: |Yfs| =14 S (typ.)
- Low leakage current: $IDSS = -10 \mu A \text{ (max) (V}_{DS} = -40 \text{ V)}$
- Enhancement mode: $V_{th} = -0.8 \text{ to} -2.0 \text{ V (V}_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characte	eristic	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-40	V	
Drain-gate voltage (R	$k_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	-40	V	
Gate-source voltage		V _{GSS}	±20	٧	
Drain current	DC (Note 1)	ΙD	-7.5	Α	
Diam current	Pulsed (Note 1)	I _{DP}	-30	A	
Drain power dissipati	ain power dissipation (Tc=25°C)		30	W	
Drain power dissipati	on $(t = 10 s)$ (Note 2a)	P_{D}	2.8	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P_{D}	1.6	W	
Single-pulse avalance	ne energy (Note 3)	EAS	26	mJ	
Avalanche current		I _{AR}	-7.5	Α	
Repetitive avalanche	energy Note 2a) (Note 4)	E _{AR}	1.9	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature	range	T _{stg}	-55 to 150	°C	

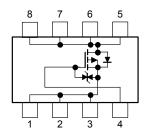
Note: For Notes 1 to 4, refer to the next page.

This transistor is an electrostatic-sensitive device. Handle with care.



Weight: 0.066 g (typ.)

Circuit Configuration

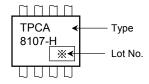




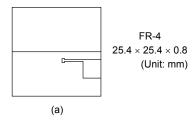
Thermal Characteristics

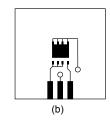
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25°C)	R _{th (ch-c)}	4.17	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	44.6	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	78.1	°C/W

Marking (Note 5)



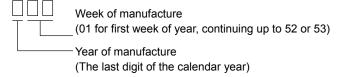
- Note 1: The channel temperature should not exceed 150°C during use.
- Note 2: (a) Device mounted on a glass-epoxy board (a)
- (b) Device mounted on a glass-epoxy board (b)





 $FR-4 \\ 25.4 \times 25.4 \times 0.8 \\ \text{(Unit: mm)}$

- Note 3: $V_{DD} = -24~V,~T_{ch} = 25^{\circ}C$ (initial), L = 0.5 mH, R_G = 25 $\Omega,~I_{AR} = -7.5~A$
- Note 4: Repetitive rating: pulse width limited by max channel temperature
- Note 5: * Weekly code: (Three digits)



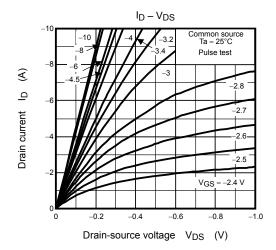


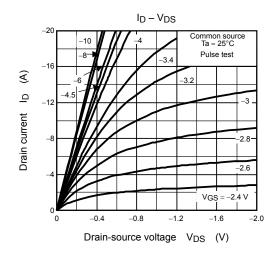
Electrical Characteristics (Ta = 25°C)

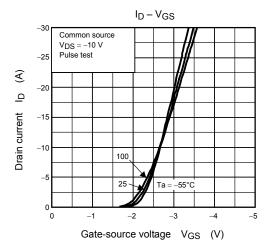
Ch	aracteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cutoff curre	ent	I _{DSS}	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain agurag bro	akdowa voltogo	V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-40	_	±10 - 10 10 2.0 29 37 24 30 14 - 190 - 70 55 - 12 - 12 43 - 43	V
Diain-source bre	akuowii voitage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-20	_	_	V
Gate threshold vo	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain course ON	rosistanos	Pro (OLI)	$V_{GS} = -4.5 \text{ V}, I_D = -3.8 \text{ A}$	_ 29 37		mO	
Drain-source ON-resistance		R _{DS} (ON)	V _{GS} = -10 V, I _D = -3.8 A	_	24	30	mΩ
Forward transfer	admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -3.8 \text{ A}$	7	14	_	S
Input capacitance	9	C _{iss}	30 13		_		
Reverse transfer capacitance Output capacitance		C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	170	_	pF
Output capacitan	put capacitance everse transfer capacitance			_	250	_	
Output capacitance Rise time	Rise time	t _r	V _{GS} 0 V		5		_
	t _{on}	-10 V GE	_	12	_		
Switching time	Fall time	t _f	$V_{DD} \simeq -20 \text{ V}$	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	- ns		
	Turn-off time	t _{off}	Duty ≦ 1%, t _w = 10 μs	_	43	_	
		Qg	$V_{DD} \simeq -32 \text{ V}, V_{GS} = -10 \text{V}$ $I_D = -7.5 \text{A}$	_	27 —		
(gate-source plus	s gate-drain)	άg	$\begin{array}{ll} V_{DD} \simeq -32~V,~V_{GS} = -5~V & I_D = \\ -7.5 A & \end{array}$	_	15	_	nC
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq -32 \text{ V}, V_{GS} = -10 \text{ V}$ $I_D = -7.5 \text{A}$		3.2	_	-
		Q _{gd}		_	8.1		
Gate switch char	Fall time Turn-off time Total gate charge gate-source plus gate-drain) Sate-source charge 1 Sate-drain ("Miller") charge			_	9.7	_	

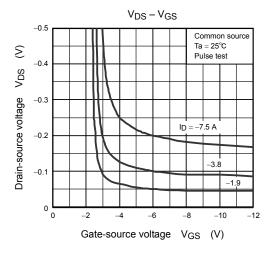
Source-Drain Ratings and Characteristics (Ta = 25°C)

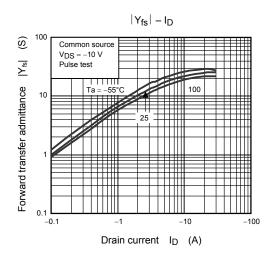
Characteri	istic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I _{DRP}	_	_	_	-30	Α
Forward voltage (diode)			V _{DSF}	$I_{DR} = -7.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

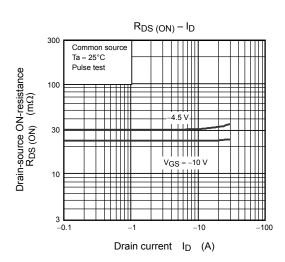




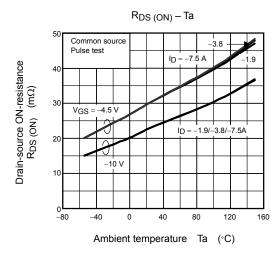


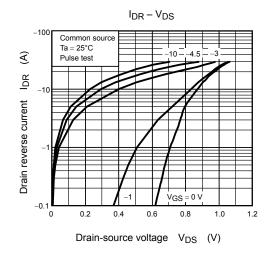


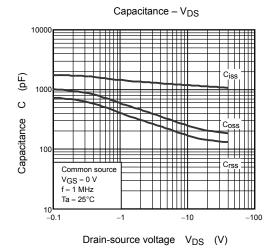


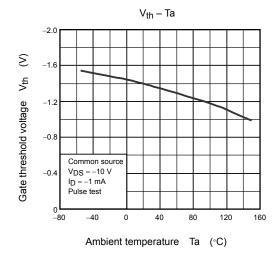


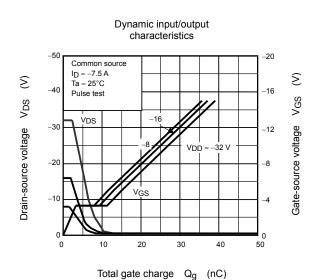
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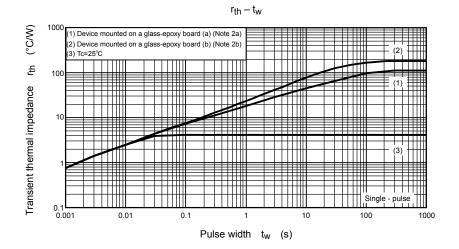


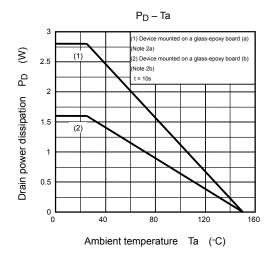


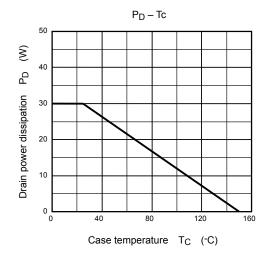


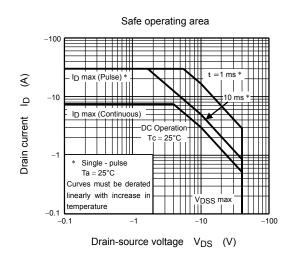


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